

• General Description

The AGM15T13F combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

This device is ideal for load switch and battery protection applications.

Product Summary

BVDSS	RDS(on)	ID
150V	9.5mΩ	78A

• Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

• Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

TO-220F Pin Configuration



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGM15T13F	AGM15T13F	TO-220F	----	----	1000

Table1. Absolute Maximum Ratings (TA=25°C)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	150	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Tc=25°C) (Note 1)	78	A
	Drain Current-Continuous(Tc=100°C)	58	A
IDM (pulse)	Drain Current-Continuous@ Current-Pulsed (Note 2)	232	A
PD	Maximum Power Dissipation(Tc=25°C)	112	W
	Maximum Power Dissipation(Tc=100°C)	45	W
EAS	Avalanche energy (Note 3)	156	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	°C

Table2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
R _{θJA}	Thermal Resistance Junction-ambient (Steady State) ¹	---	---	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	1.12	°C/W

Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250μA	150	--	--	V
IDSS	Zero Gate Voltage Drain Current	VDS=150V, VGS=0V	--	--	1	μA
IGSS	Gate-Body Leakage Current	VGS=±20V, VDS=0V	--	--	±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS, ID=250μA	2.0	--	4.0	V
gFS	Forward Transconductance	VDS=10V, ID=15A	--	20	--	S
RDS(on)	Drain-Source On-State Resistance	VGS=10V, ID=40A	--	9.5	13	mΩ
		VGS=4.5V, ID=40A	--	--	--	mΩ
Dynamic Characteristics						
Ciss	Input Capacitance	VDS=25V, VGS=0V, F=1MHZ	--	4066	--	pF
Coss	Output Capacitance		--	730	--	pF
Crss	Reverse Transfer Capacitance		--	41	--	pF
Rg	Gate resistance	VGS=0V, VDS=0V, f=1.0MHz	--	--	--	Ω
Switching Times						
td(on)	Turn-on Delay Time	VGS=10V, VDS=30V ID=40A, RGEN=2.5Ω RL=15Ω	--	15	--	ns
tr	Turn-on Rise Time		--	32.3	--	ns
td(off)	Turn-Off Delay Time		--	24	--	ns
tf	Turn-Off Fall Time		--	15	--	ns
Qg	Total Gate Charge	VGS=10V, VDS=75V, ID=70A	--	57	--	nC
Qgs	Gate-Source Charge		--	18	--	nC
Qgd	Gate-Drain Charge		--	11	--	nC
Source-Drain Diode Characteristics						
ISD	Source-Drain Current(Body Diode)		--	--	78	A
VSD	Forward on Voltage	VGS=0V, IS=40A	--	0.9	0.99	V
trr	Reverse Recovery Time	IS=30A, dI/dt=100A/μs, TJ=25°C	--	45	--	ns
Qrr	Reverse Recovery Charge		--	80	--	nc

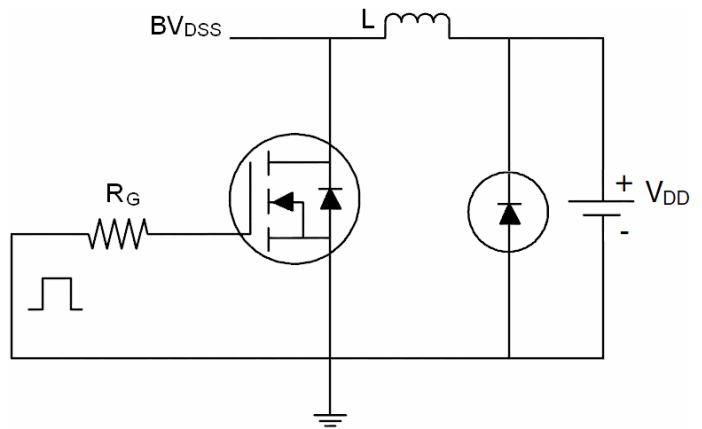
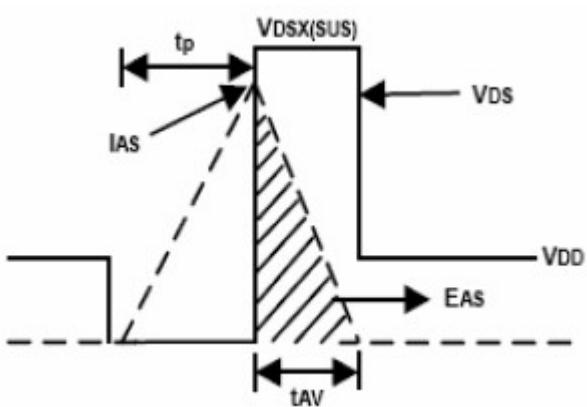
Notes 1.The maximum current rating is package limited.

Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

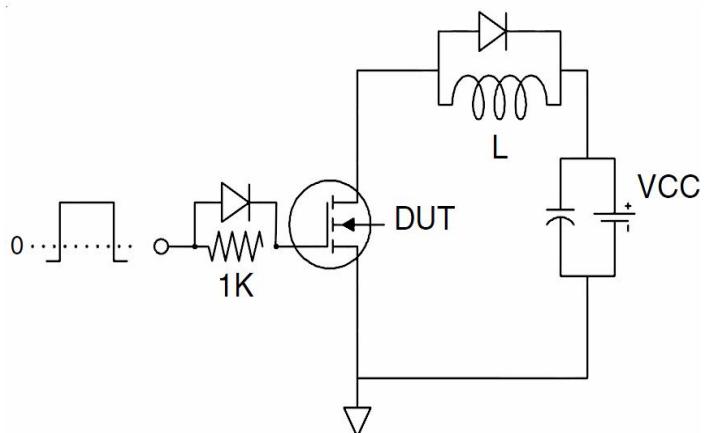
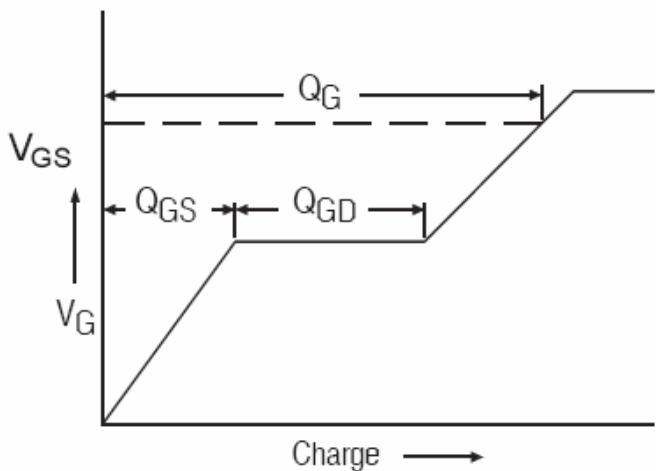
Notes 3.EAS condition: TJ=25°C

Test Circuit

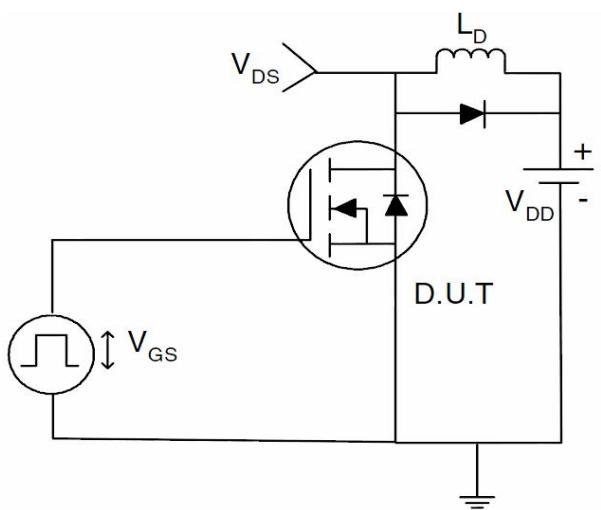
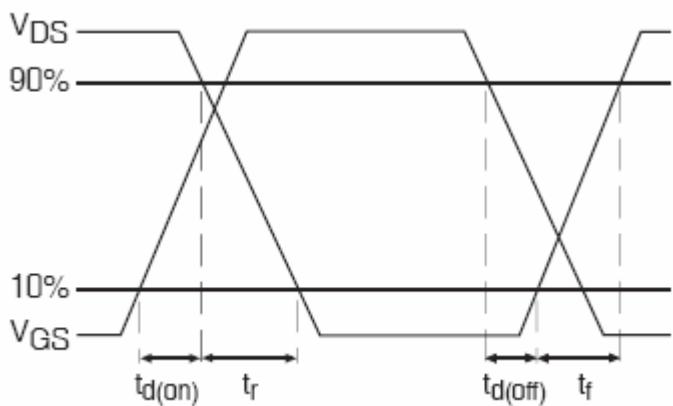
1) E_{AS} Test Circuits



2) Gate Charge Test Circuit:



3) Switch Time Test Circuit:



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (Curves)

Figure1. Output Characteristics

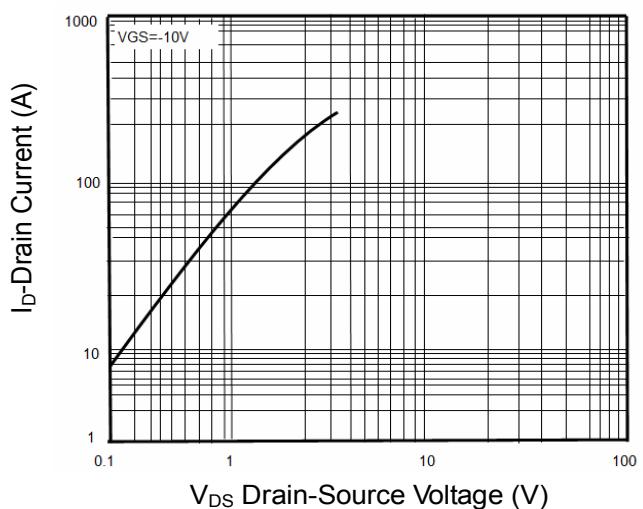


Figure2. Transfer Characteristics

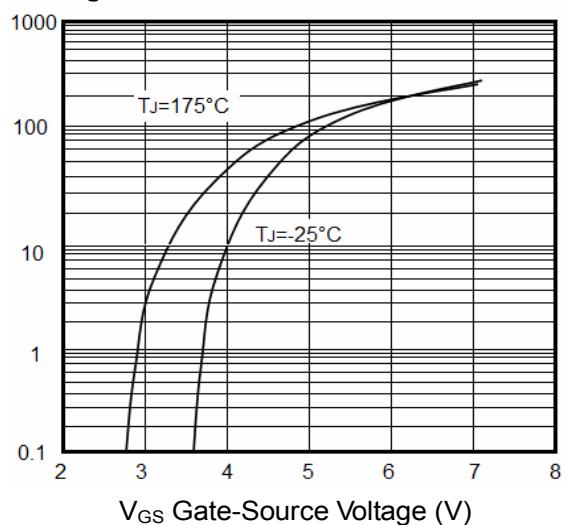


Figure3. BV_{DSS} vs Junction Temperature

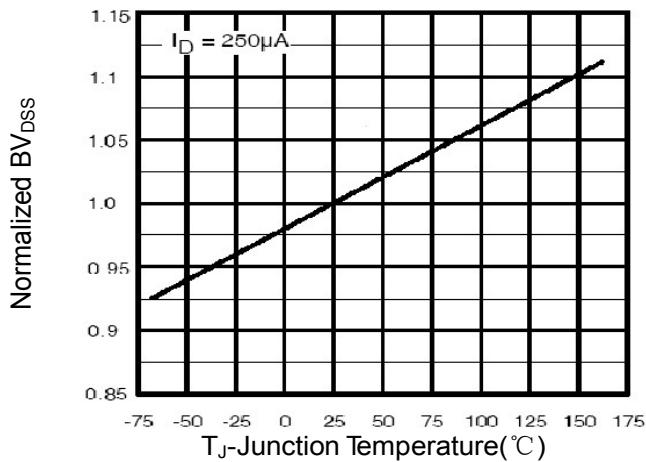


Figure4. ID vs Junction Temperature

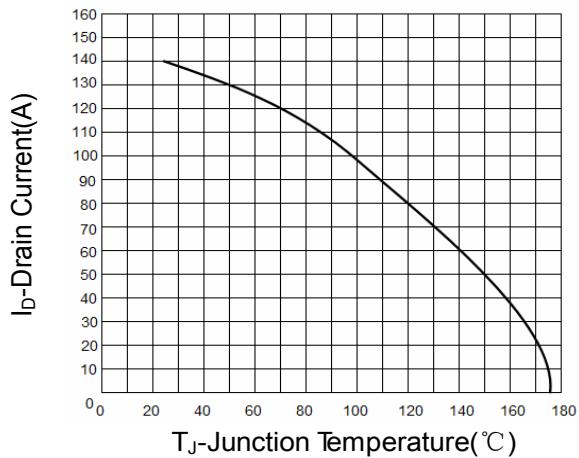


Figure5. V_{GSS(th)} vs Junction Temperature

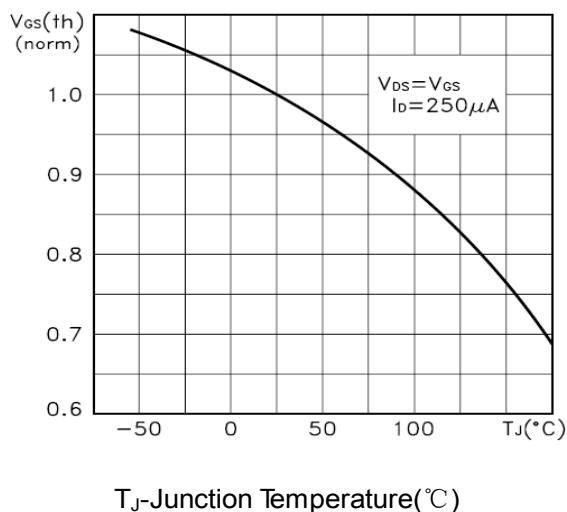


Figure6. Rdson Vs Junction Temperature

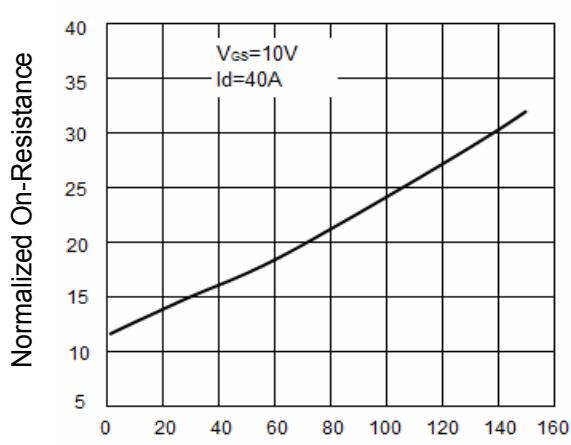
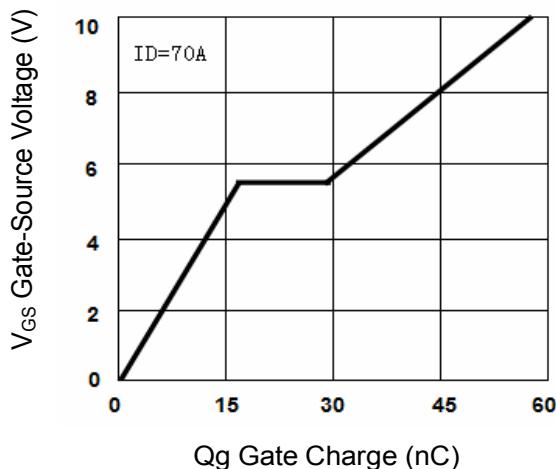
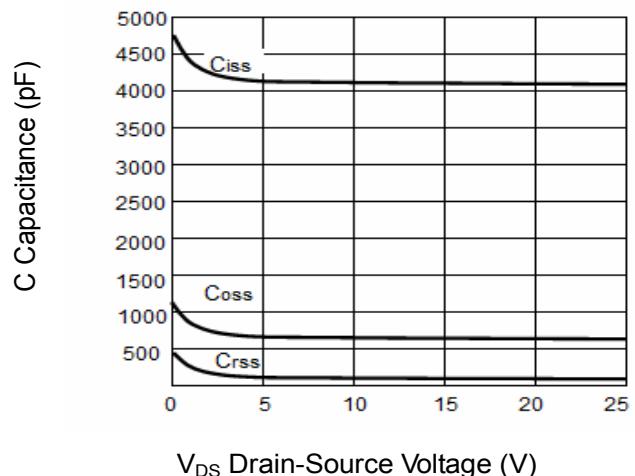
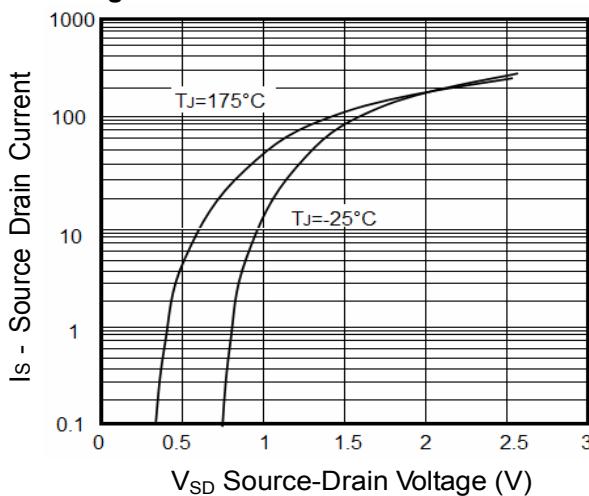
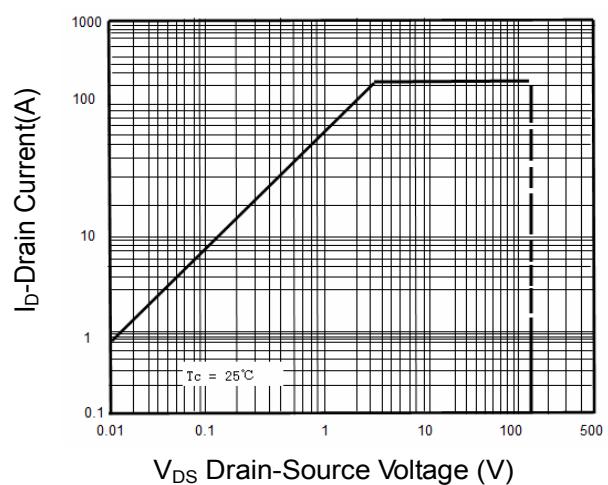
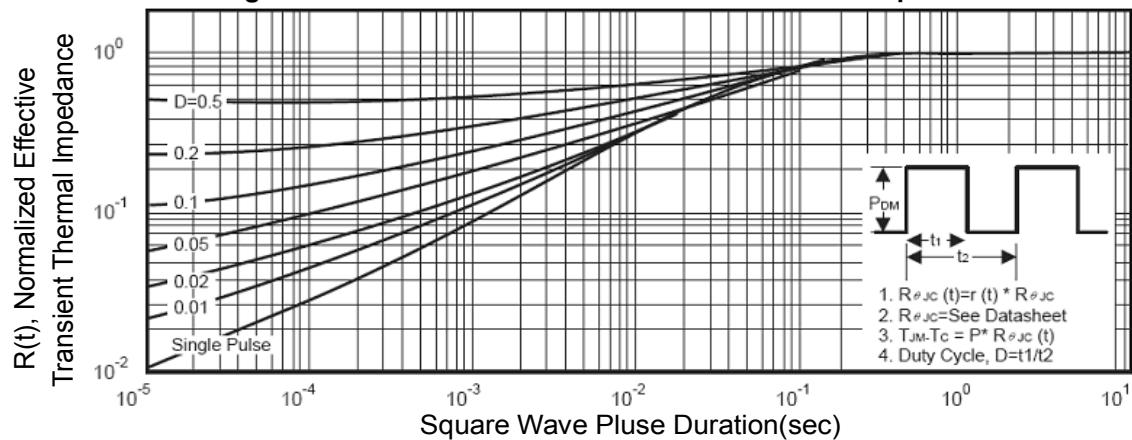
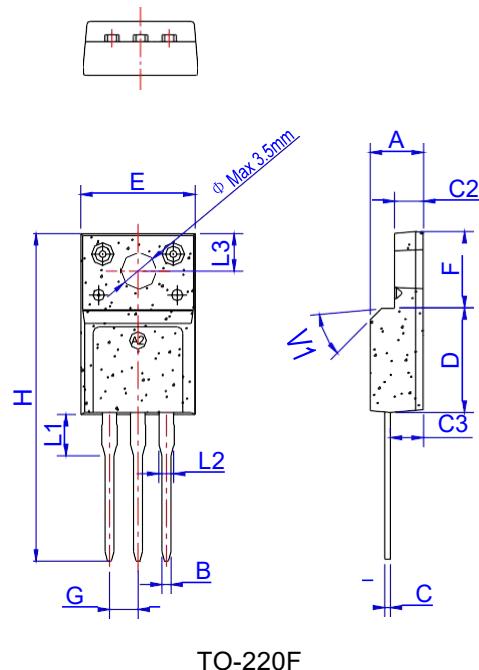


Figure7. Gate Charge

Figure8. Capacitance vs Vds

Figure9. Source- Drain Diode Forward

Figure10. Safe Operation Area

Figure11. Normalized Maximum Transient Thermal Impedance


Package Mechanical Data



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.50		4.90	0.177		0.193
B	0.74	0.80	0.83	0.029	0.031	0.033
C	0.47		0.65	0.019		0.026
C2	2.45		2.75	0.096		0.108
C3	2.60		3.00	0.102		0.118
D	8.80		9.30	0.346		0.366
E	9.80		10.4	0.386		0.410
F	6.40		6.80	0.252		0.268
G		2.54			0.1	
H	28.0		29.8	1.102		1.173
L1		3.63			0.143	
L2	1.14		1.70	0.045		0.067
L3		3.30			0.130	
V1		45°			45°	

Package Information -TO-220F

OUTLINE	TUBE (PCS)	INNER BOX (PCS)	PER CARTON (PCS)
TUBE	50	1,000	5,000

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